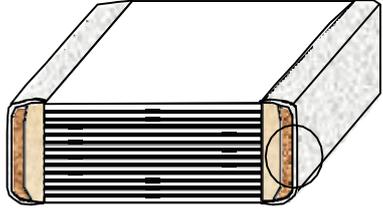
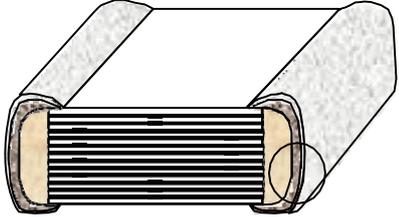
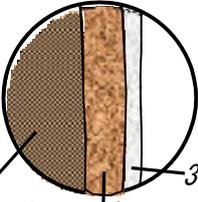
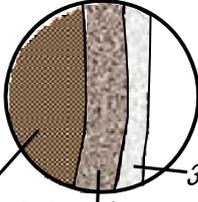


New electrode (X) product electrode structure comparison

1. Electrode structure comparison

ECHU(B)·ECWU(B)	ECHU(X)·ECWU(X)
	
<p>1.1st layer : brass 2.2nd layer : Phosphor bronze based alloy 3.3rd layer : Solder plating < External electrode structure ></p> <div style="text-align: center;">  <p>1.1st layer 2.2nd layer 3.3rd layer</p> </div>	<p>1.1st layer : brass 2.2nd layer : Conductive paste 3.3rd layer : Solder plating < External electrode structure ></p> <div style="text-align: center;">  <p>1.1st layer 2.2nd layer 3.3rd layer</p> </div>

2. Comparative test result

2.-1) Reflow solderability

(defects / tests)

Item	Both side mounting	One side mounting ※
ECHU(B)·ECWU(B)	5/1008	14/105
ECHU(X)·ECWU(X)	0/1008	0/105

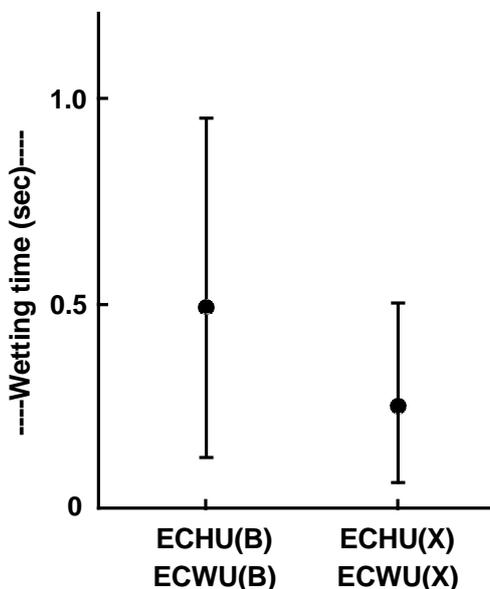
<Soldering conditions >

Cream solder thickness : 0.15 μ m

Reflow temperature : highest temperature of element surface 210 ° C

※ One side mounting : cream solder on lands on one electrode side. A test in which mounting is carried out only on the other electrode without painting

2.-2) Wettability test (meniscograph method)



2.-3) External Electrode Solder Plating Thickness

